

# XN0F256

## Silicon NPN epitaxial planar transistor

For muting circuits

### ■ Features

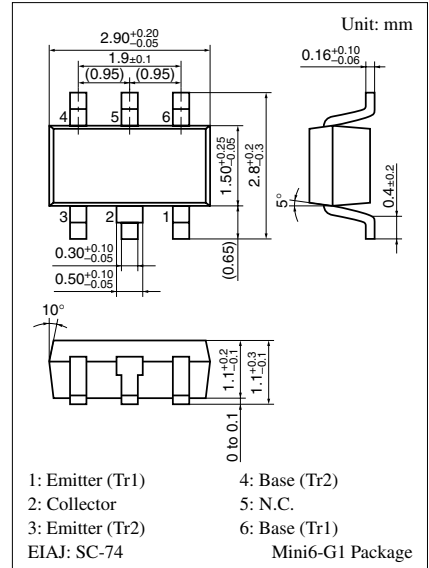
- Two elements incorporated into one package (Collector-coupled transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

### ■ Basic Part Number of Element

- UNR2226 (UN2226) × 2 elements

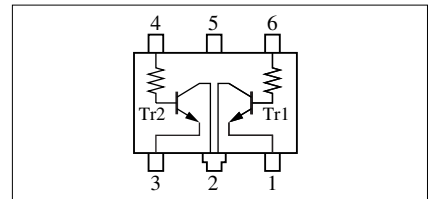
### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter		Symbol	Rating	Unit
Rating of element	Collector to base voltage	$V_{CBO}$	30	V
	Collector to emitter voltage	$V_{CEO}$	20	V
	Emitter to base voltage	$V_{EBO}$	5	V
	Collector current	$I_C$	600	mA
Total	Total power dissipation	$P_T$	300	mW
	Junction temperature	$T_j$	150	$^\circ\text{C}$
	Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$



Marking Symbol: 6A

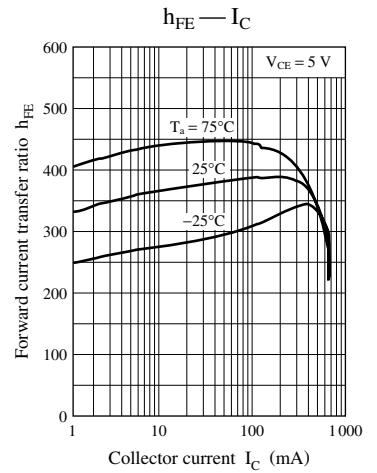
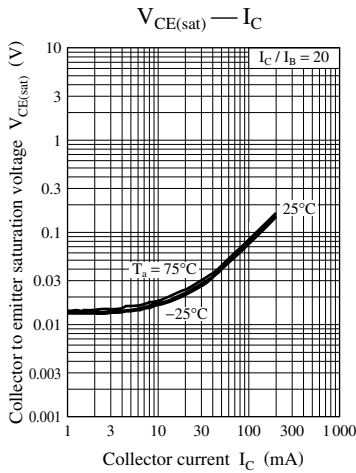
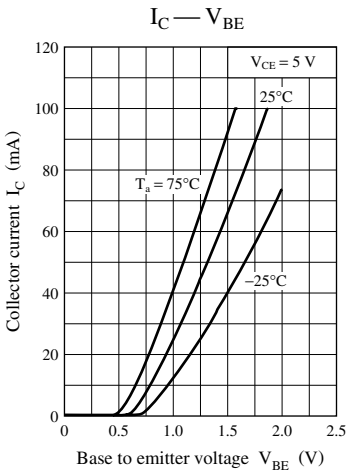
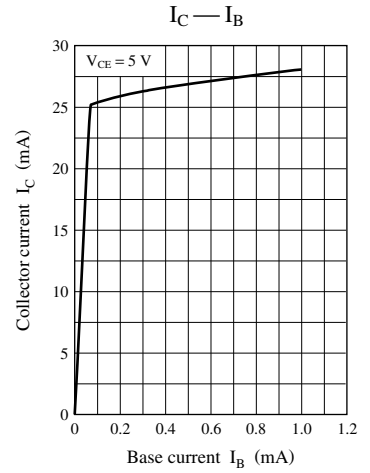
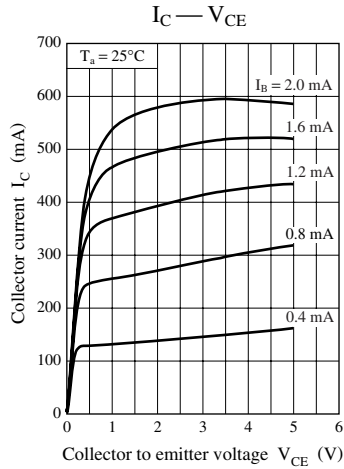
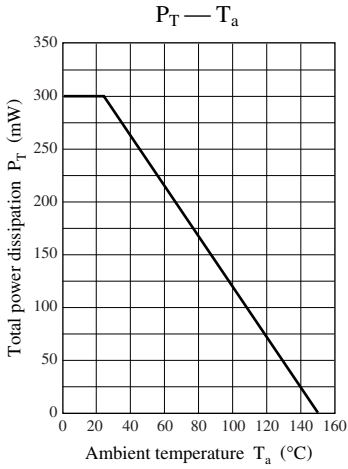
Internal Connection



### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector to base voltage	$V_{CBO}$	$I_C = 1 \mu\text{A}, I_E = 0$	30			V
Collector to emitter voltage	$V_{CEO}$	$I_C = 1 \text{mA}, I_B = 0$	20			V
Emitter to base voltage	$V_{EBO}$	$I_E = 1 \mu\text{A}, I_C = 0$	5			V
Collector cutoff current	$I_{CBO}$	$V_{CB} = 30 \text{V}, I_E = 0$			1	$\mu\text{A}$
Emitter cutoff current	$I_{EBO}$	$V_{EB} = 5 \text{V}, I_C = 0$			1	$\mu\text{A}$
Forward current transfer ratio	$h_{FE}$	$V_{CE} = 5 \text{V}, I_C = 50 \text{mA}$	100		600	—
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = 50 \text{mA}, I_B = 2.5 \text{mA}$			80	mV
Input resistance	$R_1$		-30%	4.7	+30%	k $\Omega$
Gain bandwidth product	$f_T$	$V_{CB} = 10 \text{V}, I_E = -50 \text{mA}, f = 200 \text{MHz}$		200		MHz

Note) The part number in the parenthesis shows conventional part number.



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